

SiC MOSFET P3M12025K4

N-Channel Enhancement Mode

Features

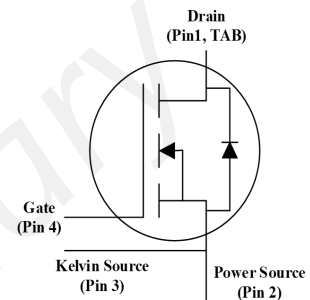
- Qualified to AEC-Q101
- High Blocking Voltage with Low On-Resistance
- High-Frequency Operation
- Ultra-Small Q_{gd}
- 100% UIS tested

Benefits

- Improve System Efficiency
- Increase Power Density
- Reduce Heat Sink Requirements
- Reduction of System Cost

Applications

- Solar Inverters
- EV Battery Chargers
- High Voltage DC/DC Converters
- Switch Mode Power Supplies



TO-247-4

Drain	1
Power Source	2
Kelvin Source	3
Gate	4



Order Information

Part Number	Package	Marking
P3M12025K4	TO-247-4	P3M12025K4

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1. Maximum Ratings

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value	Unit	Test Conditions
Drain - Source Voltage	V_{DSmax}	1200	V	$V_{GS} = 0V$ $I_D = 100\mu A$
Gate - Source Voltage (dynamic)	V_{GSmax}	-8 / +22	V	Duty cycle $\leq 1\%$
Gate - Source Voltage(static) turn-on gate voltage turn-off gate voltage	$V_{GS,on}$ $V_{GS,off}$	+15 / +18 -3	V	Static
Continuous Drain Current	I_D	75	A	$V_{GS} = 18V$ $T_C = 25^\circ\text{C}$
		53		$V_{GS} = 18V$ $T_C = 100^\circ\text{C}$
		71		$V_{GS} = 15V$ $T_C = 25^\circ\text{C}$
		50		$V_{GS} = 15V$ $T_C = 100^\circ\text{C}$
Pulsed Drain Current	$I_{D(pulse)}$	200	A	$PW \leq 10\mu s$, Duty cycle $\leq 1\%$
Power Dissipation	P_D	375	W	
Operating Junction	T_J	-55 To +175	$^\circ\text{C}$	
Storage Temperature	T_{stg}	-55 To +175	$^\circ\text{C}$	
Solder Temperature	T_L	260	$^\circ\text{C}$	
Mounting Torque	M_d	1 8.8	Nm lbf-in	M3 or 6-32 screw

2. Electrical Characteristics

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1200	/	/	V	$V_{GS} = 0V$ $I_D = 1.5mA$
Gate Threshold Voltage	$V_{GS(th)}$	2.0	2.6	/	V	$V_{DS} = V_{GS}$ $I_D = 10mA$ $T_J = 25^\circ\text{C}$
		/	2.0	/	V	$V_{DS} = V_{GS}$ $I_D = 10mA$ $T_J = 175^\circ\text{C}$
Reverse Bias Drain Current	I_{DSS}	/	1	100	μA	$V_{GS} = 0V$ $V_{DS} = 1200V$
Gate-Source Leakage Current	I_{GSS}	/	1	250	nA	$V_{GS} = -5 \sim 18V$ $V_{DS} = 0V$
Drain-Source On-State Resistance	$R_{DS(on)}$	/	25	35	m Ω	$V_{GS} = 18V$ $I_D = 40A$ $T_J = 25^\circ\text{C}$
		/	40	/		$V_{GS} = 18V$ $I_D = 40A$ $T_J = 175^\circ\text{C}$
		/	29	/		$V_{GS} = 15V$ $I_D = 40A$ $T_J = 25^\circ\text{C}$
		/	43	/		$V_{GS} = 15V$ $I_D = 40A$ $T_J = 175^\circ\text{C}$
Transconductance	g_{fs}	/	21	/	S	$V_{DS} = 20V$ $I_{DS} = 40A$ $T_J = 25^\circ\text{C}$
		/	20	/		$V_{DS} = 20V$ $I_{DS} = 40A$ $T_J = 175^\circ\text{C}$

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Parameter	Symbol	Value			Unit	Test Conditions	
		Min.	Typ.	Max.			
Input Capacitance	C _{iss}	/	3800	/	pF	V _{GS} = 0V V _{DS} = 800V f= 1MHz V _{AC} = 25mV	
Output Capacitance	C _{Oss}	/	143	/			
Reverse Transfer Capacitance	C _{rss}	/	7.4	/			
Coss Stored Energy	E _{Oss}	/	50	/	μJ		
Turn-on Energy	E _{on}	/	237	/	μJ	V _{DS} = 800V V _{GS} = -3/15V I _D = 30A R _G = 1Ω	
Turn-off Energy	E _{off}	/	86	/			
Turn-On Delay Time	T _{d(on)}	/	30	/	ns		
Rise Time	T _r	/	17	/			
Turn-Off Delay Time	T _{d(off)}	/	34	/			
Fall Time	T _f	/	9	/			
Turn-on Energy	E _{on}	/	200	/	μJ		V _{DS} = 800V V _{GS} = -4/18V I _D = 30A R _G = 1Ω
Turn-off Energy	E _{off}	/	71	/			
Turn-On Delay Time	T _{d(on)}	/	27	/	ns		
Rise Time	T _r	/	15	/			
Turn-Off Delay Time	T _{d(off)}	/	36	/			
Fall Time	T _f	/	9	/			
Internal Gate Resistance	R _{G(int)}	/	1.3	/	Ω	f= 1MHz V _{AC} = 25mV	

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Gate to Source Charge	Q_{gs}	/	47	/	nC	$V_{DS} = 800V$ $I_{DS} = 40A$ $V_{GS} = -3/15V$ $I_G = 5mA$
Gate to Drain Charge	Q_{gd}	/	49	/		
Total Gate Charge	Q_g	/	116	/		
Gate to Source Charge	Q_{gs}	/	45	/	nC	$V_{DS} = 800V$ $I_{DS} = 40A$ $V_{GS} = -4/18V$ $I_G = 5mA$
Gate to Drain Charge	Q_{gd}	/	51	/		
Total Gate Charge	Q_g	/	134	/		

PNJ Preliminary

3. Reverse Diode Characteristics

At $T_J = 25^\circ\text{C}$, unless specified otherwise

Parameter	Symbol	Value		Unit	Test Conditions
		Typ.	Max.		
Diode Forward Voltage	V_{SD}	5.5	/	V	$V_{GS} = -3\text{V}$ $I_{SD} = 20\text{A}$ $T_J = 25^\circ\text{C}$
		5.2	/	V	$V_{GS} = -3\text{V}$ $I_{SD} = 20\text{A}$ $T_J = 175^\circ\text{C}$
Continuous Diode Forward Current	I_S	/	63	A	$V_{GS} = -3\text{V}$
Reverse Recover Time	t_{rr}	11	/	ns	$V_{GS} = -3/15\text{V}$ $I_{SD} = 30\text{A}$ $V_R = 800\text{V}$ $dI/dt = 3250\text{A}/\mu\text{s}$ $T_J = 25^\circ\text{C}$
Reverse Recovery Charge	Q_{rr}	59	/	nC	
Peak Reverse Recovery Current	I_{rrm}	18	/	A	
Reverse Recover Time	t_{rr}	10	/	ns	$V_{GS} = -4/18\text{V}$ $I_{SD} = 30\text{A}$ $V_R = 800\text{V}$ $dI/dt = 3500\text{A}/\mu\text{s}$ $T_J = 25^\circ\text{C}$
Reverse Recovery Charge	Q_{rr}	55	/	nC	
Peak Reverse Recovery Current	I_{rrm}	21	/	A	

4. Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.43	$^\circ\text{C}/\text{W}$

5. Typical Performance

At $T_J = 25^\circ\text{C}$, unless specified otherwise

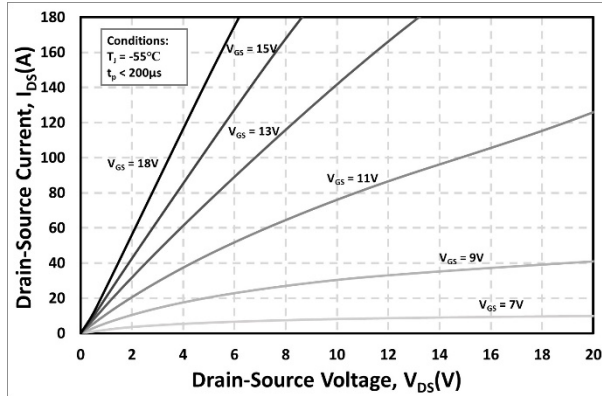


Figure 1. Output Characteristics $T_J = -55^\circ\text{C}$

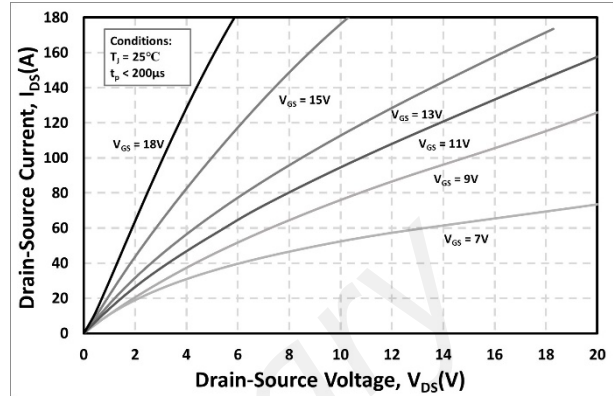


Figure 2. Output Characteristics $T_J = 25^\circ\text{C}$

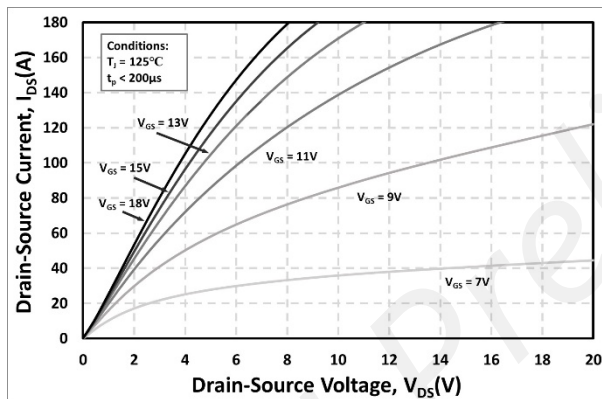


Figure 3. Output Characteristics $T_J = 125^\circ\text{C}$

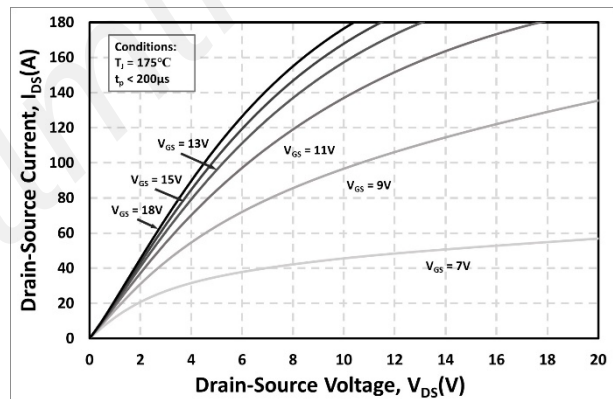


Figure 4. Output Characteristics $T_J = 175^\circ\text{C}$

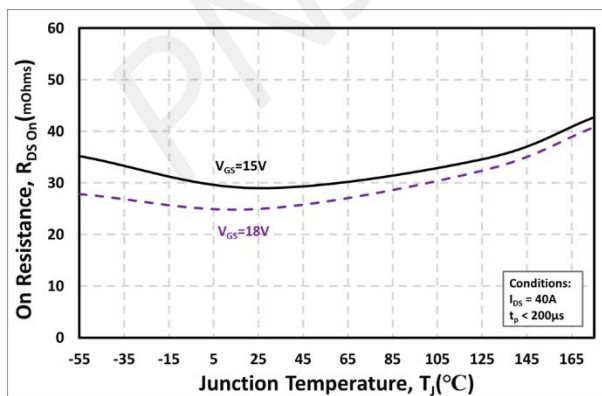


Figure 5. Normalized On-Resistance vs. Temperature

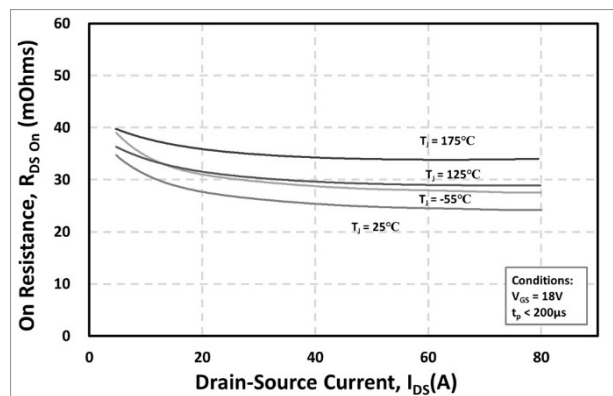


Figure 6. On-Resistance vs. Drain Current Various Temperatures

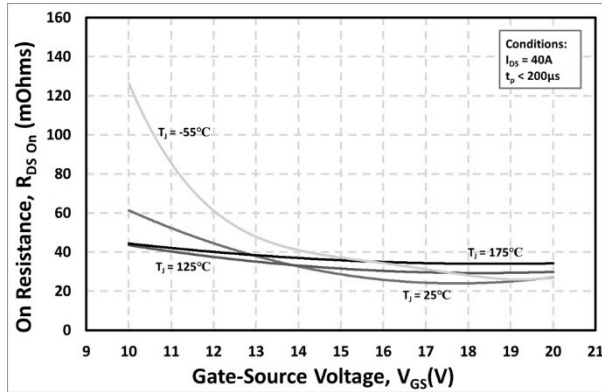


Figure 7. On-Resistance vs. Gate-Source Voltage

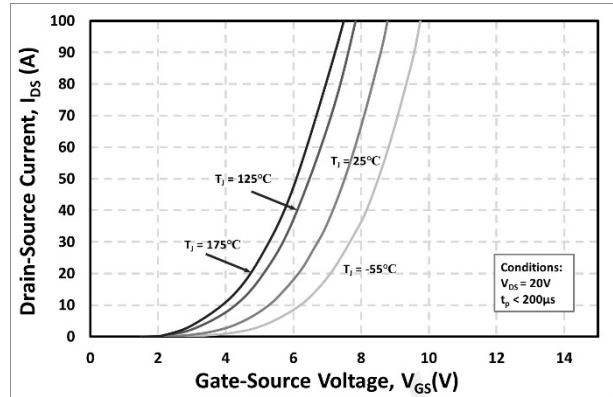


Figure 8. Transfer Characteristic for Various Junction Temperatures

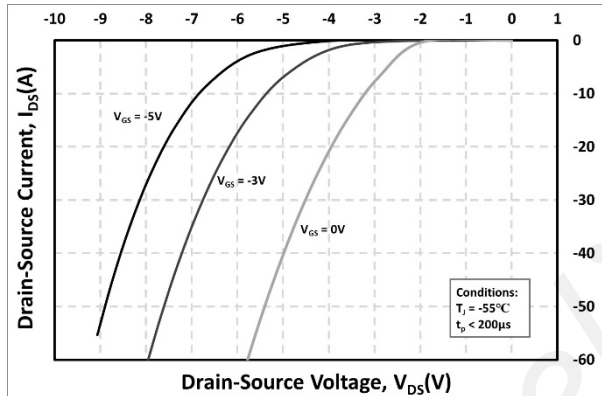


Figure 9. Body Diode Characteristic at -55°C

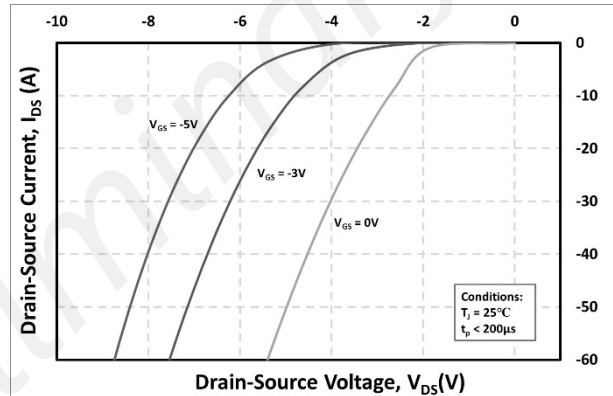


Figure 10. Body Diode Characteristic at 25°C

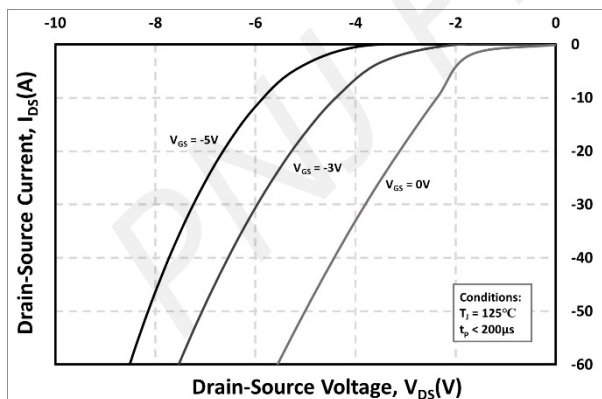


Figure 11. Body Diode Characteristic at 125°C

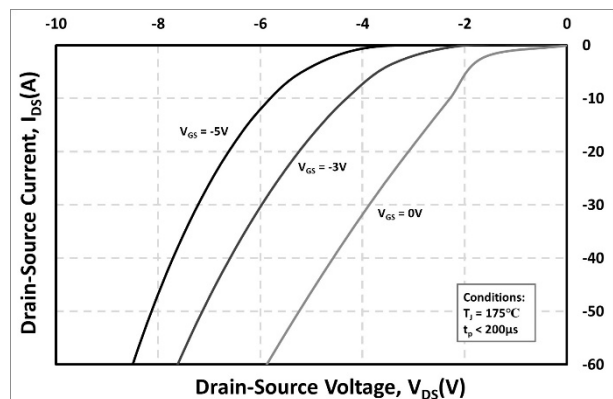


Figure 12. Body Diode Characteristic at 175°C

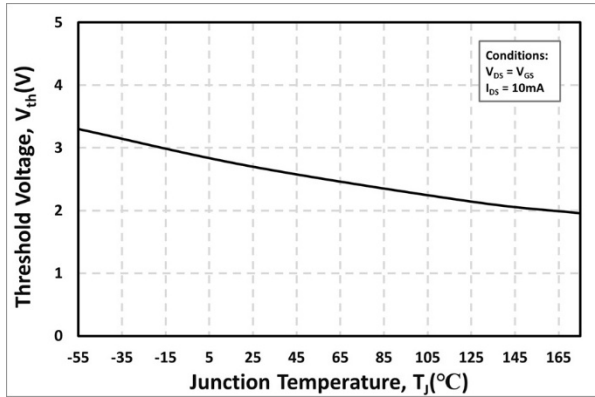


Figure 13. Threshold Voltage vs. Temperature

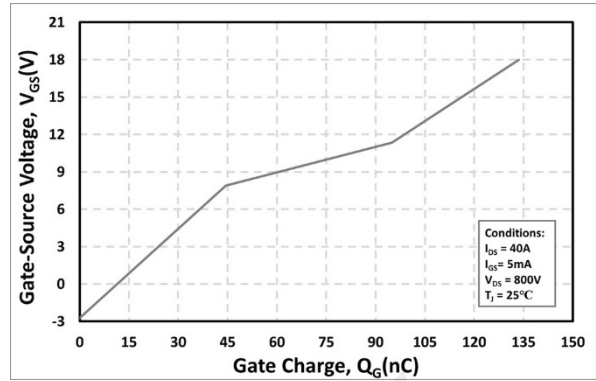


Figure 14. Gate Charge Characteristics

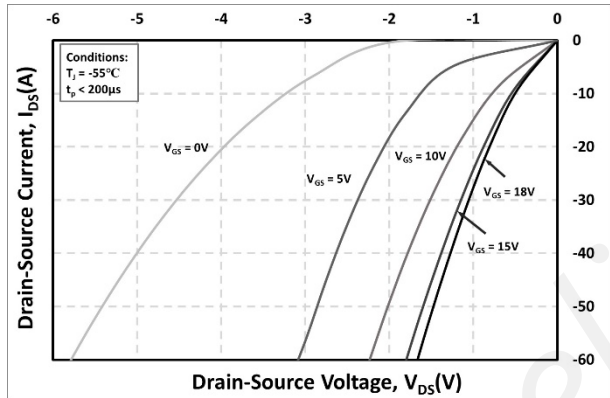


Figure 15. 3rd Quadrant Characteristic at -55°C

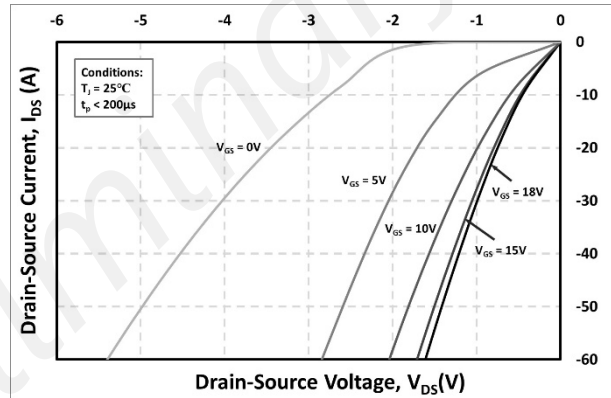


Figure 16. 3rd Quadrant Characteristic at 25°C

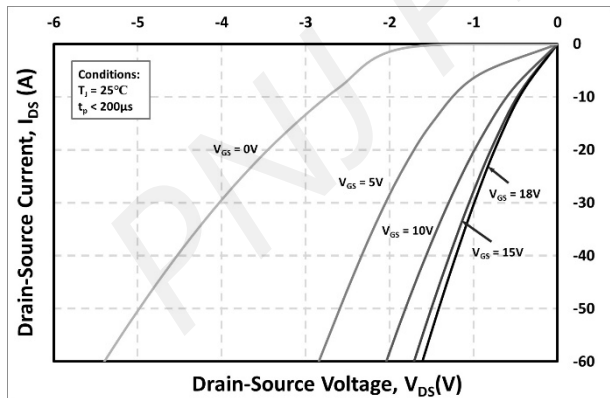


Figure 17. 3rd Quadrant Characteristic at 125°C

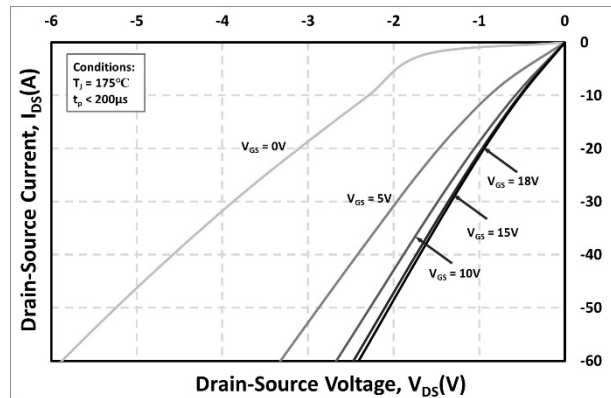


Figure 18. 3rd Quadrant Characteristic at 175°C

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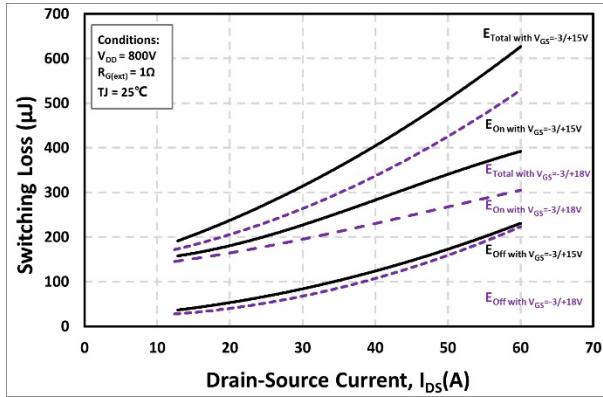


Figure 19. Clamped Inductive Switching Energy vs. Drain Current ($V_{DS} = 800V$)

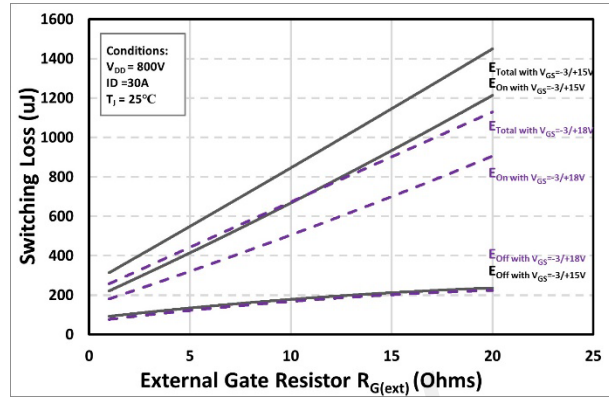


Figure 20. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

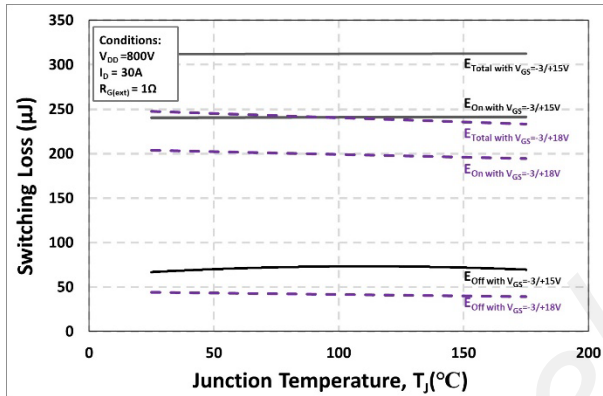


Figure 21. Clamped Inductive Switching Energy vs. Temperature

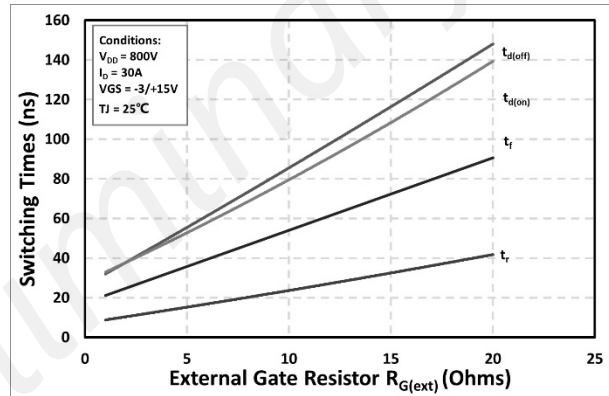


Figure 22. Switching Times vs. $R_{G(ext)}$

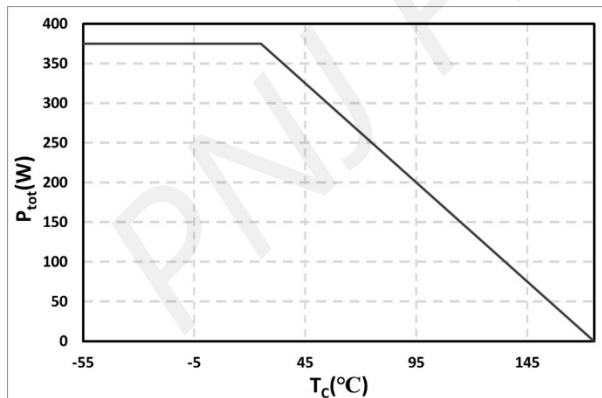


Figure 23. Maximum Power Dissipation Derating vs. Case Temperature

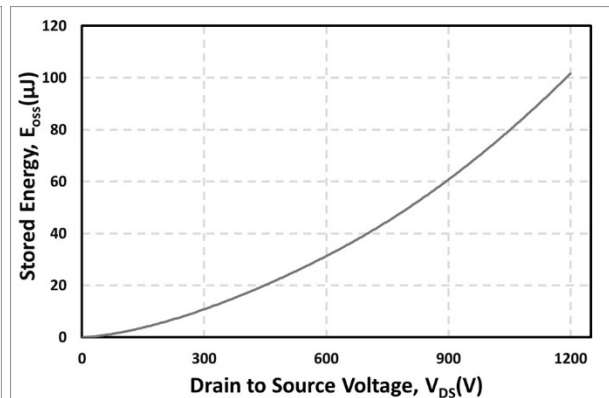


Figure 24. Output Capacitor Stored Energy

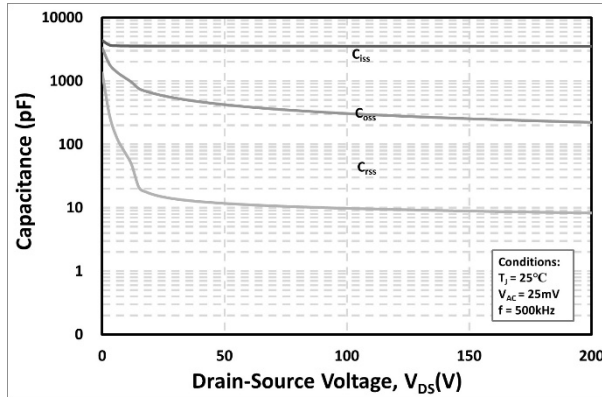


Figure 25. Capacitances vs. Drain-Source Voltage (0 - 200V)

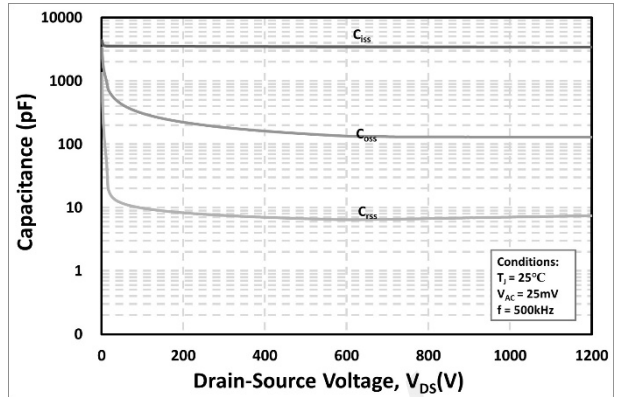


Figure 26. Capacitances vs. Drain-Source Voltage (0 - 1200V)

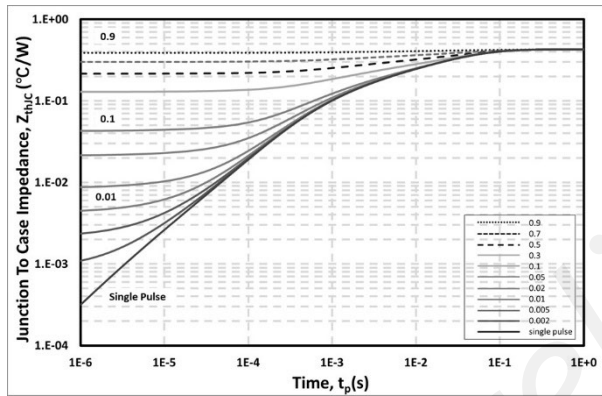


Figure 27. Transient Thermal Impedance (Junction - Case)

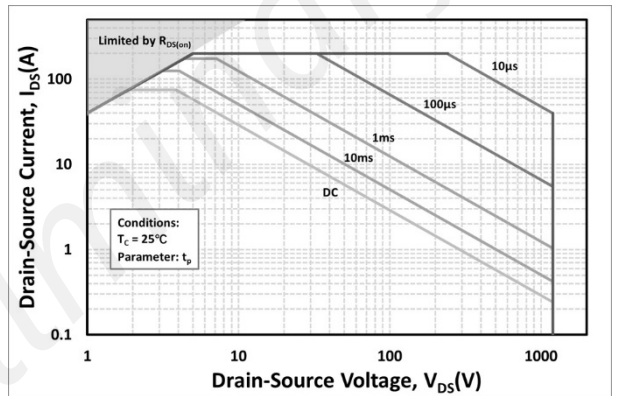


Figure 28. Safe Operating Area

6. Definitions

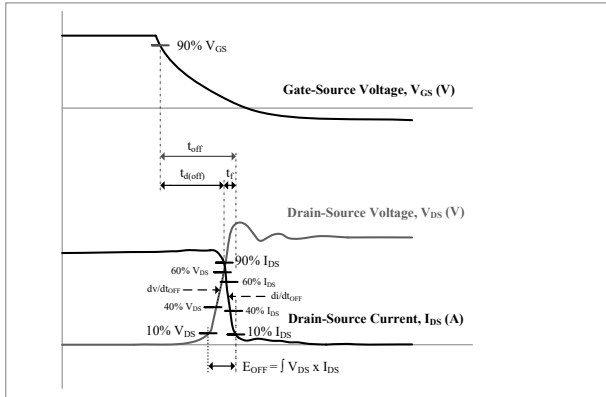


Figure 29. Turn-off Transient Definitions

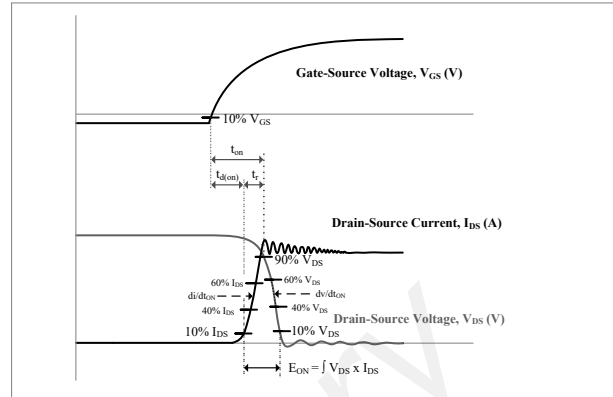


Figure 30. Turn-on Transient Definitions

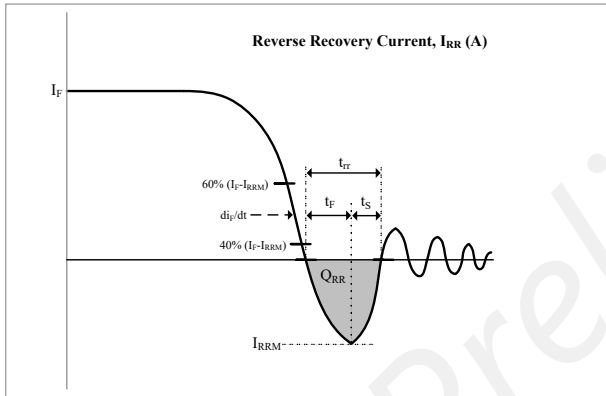


Figure 31. Reverse Recovery Definitions

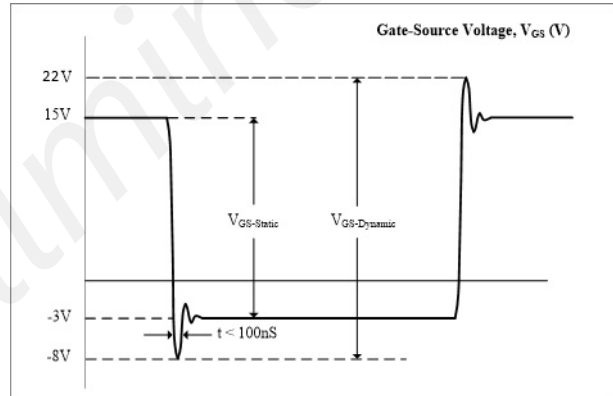
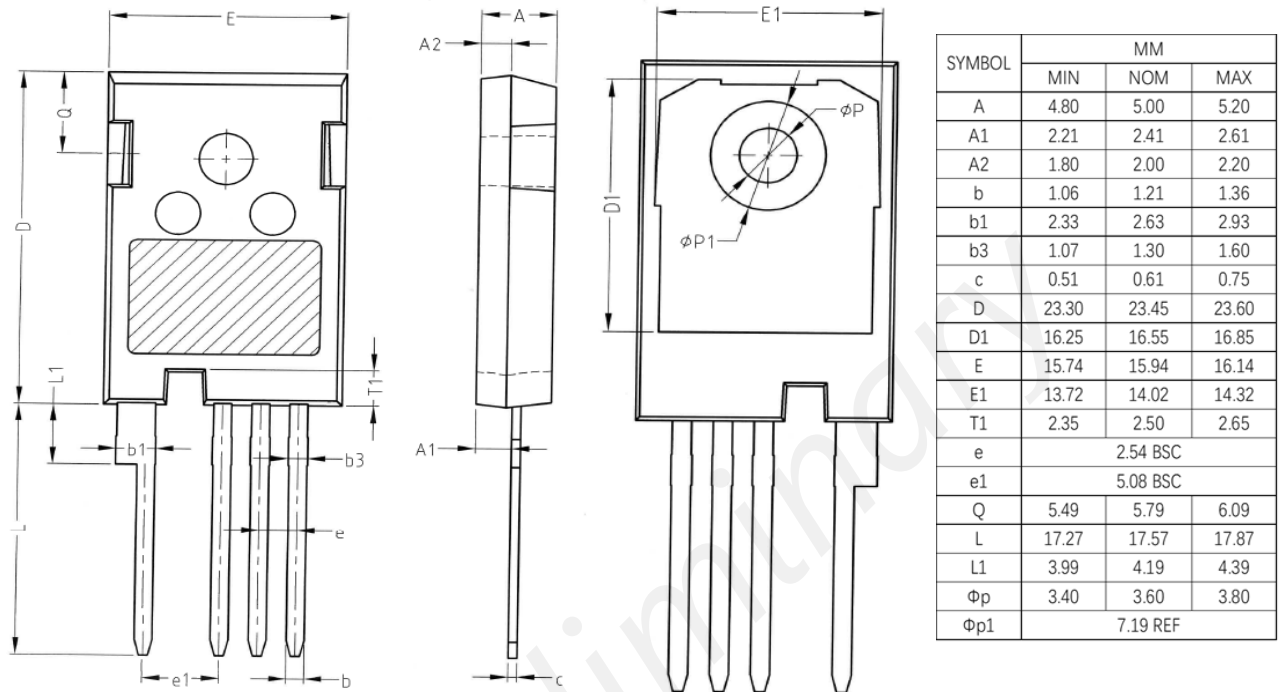


Figure 32. V_GS Transient Definitions

7. Package Outlines



Drawing and Dimensions

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